

General

- Chip size from 0603 to 1206
- Resistance value from 1mΩ to 20mΩ
- Low thermal EMF
- Low TCR
- Lead free, RoHS compliant for global
- Applications and halogen free

Application

- Switching model power supply.
- Battery pack.
- Notebook, personal computer.
- Test Instrument.
- Power Amplifier.

Electrical Specifications

Type	Power Rating at 70°C(W)	Resistance Range (mΩ)	TCR (ppm/°C)	Resistance tolerance	Operation Temp. Range
0603	0.3	2≤R≤5	±100	±1%(F)	-55°C~+155°C
		6≤R≤20	±75		
0805	0.5	2≤R≤5	±75		
		6≤R≤20	±50		
1206	1.0	1	±75	±1%(F)	
		2≤R≤4	±75	±1.5%(E)	
		5≤R≤20	±50	±1%(F)	

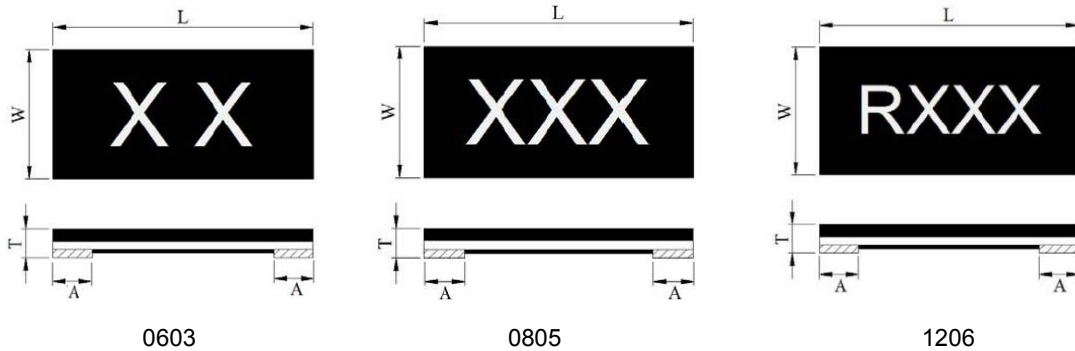
Part Number information

SMB 12 A 1 E R002 I

【1】 【2】 【3】 【4】 【5】 【6】 【7】

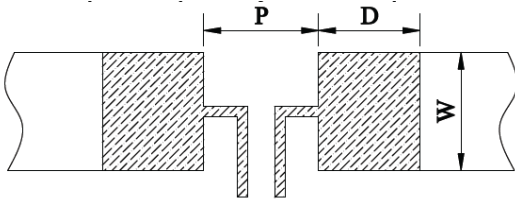
- 【1】** Series Name: SART Metal Foil PCB Type
- 【2】** Chip size: 12:1206 08:0805 06:0603
- 【3】** Material Code:A:Alloy
- 【4】** Power Code:1:1W A:0.5W M:0.3W
- 【5】** Resistance Tolerance: F:±1% E: ±1.5%
- 【6】** Resistance Code: R002=2mΩ
- 【7】** Packaging Code: T:Tape& Reel B:Bulk Pack

Dimensions



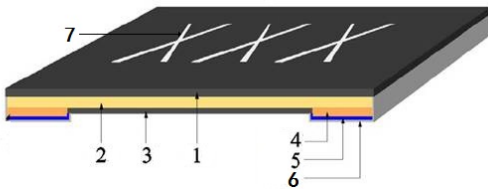
Type	Resistance Range (mΩ)	W (mm)	L (mm)	T (mm)	A (mm)
0603	2	0.80±0.25	1.60±0.25	0.40±0.25	0.45±0.20
	2.5<R≤3	0.80±0.25	1.60±0.25	0.40±0.25	0.35±0.20
	4≤R≤20	0.80±0.25	1.60±0.25	0.40±0.25	0.30±0.20
0805	2	1.25±0.25	2.00±0.25	0.40±0.25	0.60±0.20
	3≤R≤20	1.25±0.25	2.00±0.25	0.40±0.25	0.40±0.20
1206	1	1.60±0.25	3.20±0.25	0.40±0.25	1.25±0.30
	2	1.60±0.25	3.20±0.25	0.40±0.25	1.05±0.30
	3	1.60±0.25	3.20±0.25	0.40±0.25	0.80±0.30
	4≤R≤20	1.60±0.25	3.20±0.25	0.40±0.25	0.60±0.30

Recommended Land Patterns



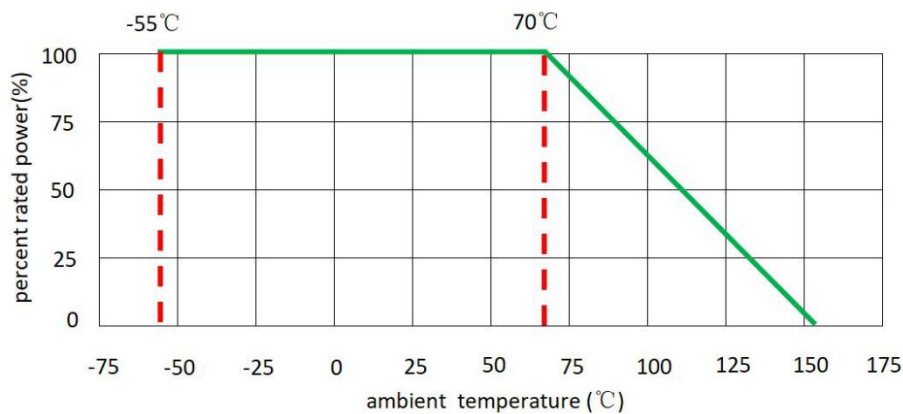
Type	Resistance range (mΩ)	P (mm)	W (mm)	D (mm)
0603	2	0.50	0.92	1.35
	$2.5 \leq R \leq 20$	0.60	0.92	1.30
0805	2	0.50	1.44	1.55
	$3 \leq R \leq 20$	0.80	1.44	1.40
1206	1	0.50	1.84	2.15
	2	0.60	1.84	2.10
	$3 \leq R \leq 20$	1.20	1.84	1.80

Materials



No.	Materials	No.	Materials
1	Epoxy substrate	5	Nickel
2	Alloy	6	Tin
3	Protective coating	7	Marking
4	Copper	/	/

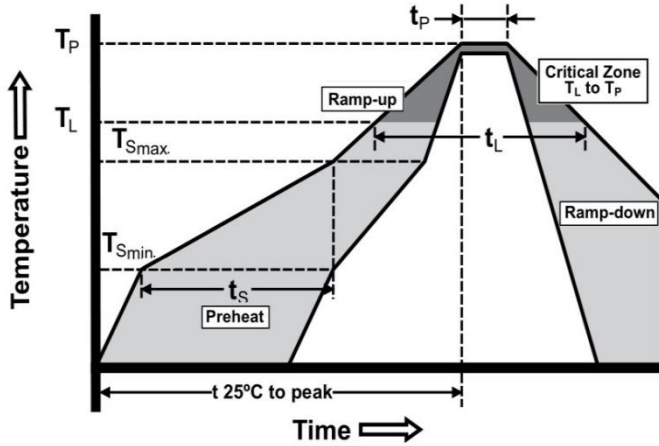
Power Derating Curve



Recommended Solder Curve

1. Infrared Reflow

- Temperature: 260°C
- Time: 5sec Max.
- Recommend Reflow profile:



Profile Feature	Pb-Free Assembly
Average Ramp-up Rate (T _{Smax} to T _P)	3°C/sec Max.
Preheat Temperature Min.(T _{Smin}) Temperature Max.(T _{Smax}) Time(T _{Smin} to T _{Smax})	150°C 200°C 60sec~120sec
Peak Temperature(T _P)	260°C
Time within 5°C of actual Peak Temperature(T _P)	5sec
Melting tin time(T _L)	20sec~30sec
Ramp-down Rate	6°C/sec Max.
Time 25°C to peak Temperature	8 min Max.

2. Wave soldering

- Reservoir Temperature: 260°C
- Time in Reservoir: 10sec Max.

3. Hand Soldering

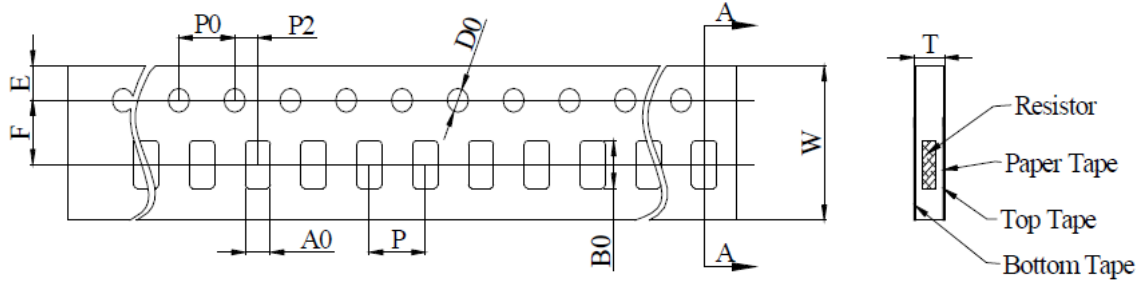
- Temperature: 350°C
- Time: 5sec Max.

Product Characteristics

Item	Test condition / Methods	Performance	Standard
Short Time Overload	0805 $2m\Omega \leq R \leq 10m\Omega$: $P = 5*Pr$; 1206 $1m\Omega \leq R \leq 10m\Omega$: $P = 5*Pr$; $T=25^{\circ}C \pm 2^{\circ}C$, $t = 5sec$ Rest specifications: $P=2.5*Pr$; $T=25 \pm 2^{\circ}C$, $t = 5sec$	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC 60115-1 4.13
Temperature Coefficient of Resistance (TCR)	$TCR = (R - R_0) / R_0 (T_2 - T_1) \times 10^6$ T_1 T_2 Test temperature: $+25^{\circ}C \sim +125^{\circ}C$	Refer to SART Spec	IEC 60115-1 4.8
Thermal Shock	$-55^{\circ}C$ (30min) / $+150^{\circ}C$ (30min) , 100 cycles	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC 60115-1 4.19
Resistance to Solder Heat	$270^{\circ}C \pm 5^{\circ}C$, 20sec \pm 1sec	$ \Delta R \leq \pm(1\% + 0.5m\Omega)$	IEC 60115-1 4.18
Solderability	$245^{\circ}C \pm 5^{\circ}C$, 3sec \pm 0.5sec	95% coverage Min.	IEC 60115-1 4.17
Load Life	1000 hours at rated power, $70^{\circ}C \pm 2^{\circ}C$, 1.5hours "ON", 0.5hours "OFF"	$ \Delta R \leq \pm(2\% + 0.5 m\Omega)$	IEC 60115-1 4.25
Moisture Load Life (60°C、95%RH)	$T=60^{\circ}C \pm 2^{\circ}C$; RH=95% ; $V_{test} = V_{max}$; $t= 1.5hours$ "ON" , 0.5hours "OFF", 1000hours	$ \Delta R \leq \pm(2\% + 0.5 m\Omega)$	IEC 60115-1 4.24
Bending test	Bending width 2mm, Epoxy thickness 1.6mm, Fulcrums distance 90mm	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC 60115-1 4.33
High Temp. Exposure	$170^{\circ}C \pm 2^{\circ}C$, 1000hours	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC60115-1 4.25
Low Temp. Storage	$-55^{\circ}C \pm 2^{\circ}C$, 1000hours	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC60115-1 4.25
Mechanical Shock	$a = 100G$, $t = 11ms$, 5 times shock	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC60115-1 4.21

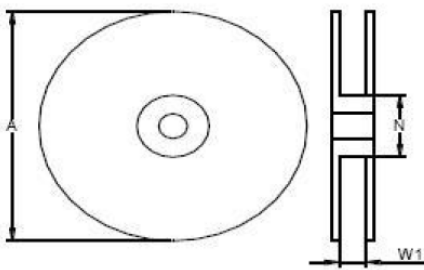
Packaging

1. Embossed Tape Dimensions



Type	A0 (mm)	B0 (mm)	W (mm)	F (mm)	E (mm)
0603	1.18±0.20	1.98±0.20	8.00±0.30	3.50±0.10	1.75±0.10
0805	1.68±0.20	2.38±0.20	8.00±0.30	3.50±0.10	1.75±0.10
1206	2.05±0.20	3.65±0.20	8.00±0.30	3.50±0.10	1.75±0.10
Type	P (mm)	P2 (mm)	P0 (mm)	D0 (mm)	T (mm)
0603	4.00±0.10	2.00±0.10	4.00±0.10	1.50±0.10	0.58±0.10
0805	4.00±0.10	2.00±0.10	4.00±0.10	1.50±0.10	0.58±0.20
1206	4.00±0.10	2.00±0.10	4.00±0.10	1.50±0.10	0.58±0.20

2. Reel Dimensions

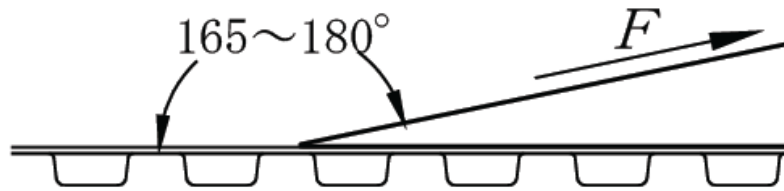


Type	A (mm)	N (mm)	W1 (mm)
0603	178.00±5.00	60.00±2.00	9.00±1.00
0805			
1206			

3. Quantity of Package

Type	0603	0805	1206
Quantity(pcs)	5000		

4. Peeling Test



F=Peeling Strength:0.1-1.0N(10~100gf)

Storage

- The ambient temperature shall be between 5°C~30°C.
- The relative humidity recommended for storage is between 25%RH~60%RH.
- Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.